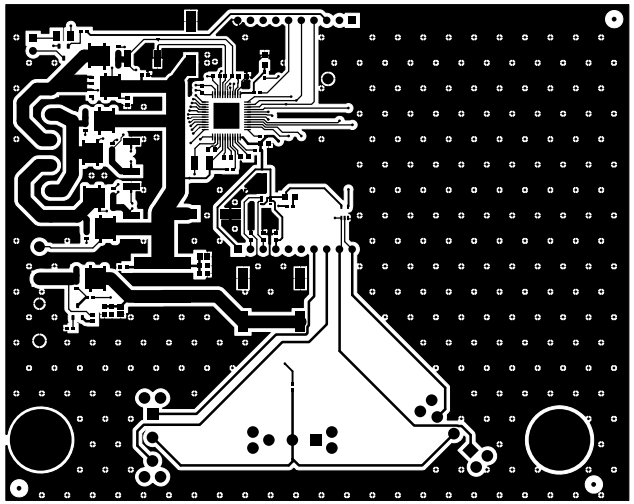
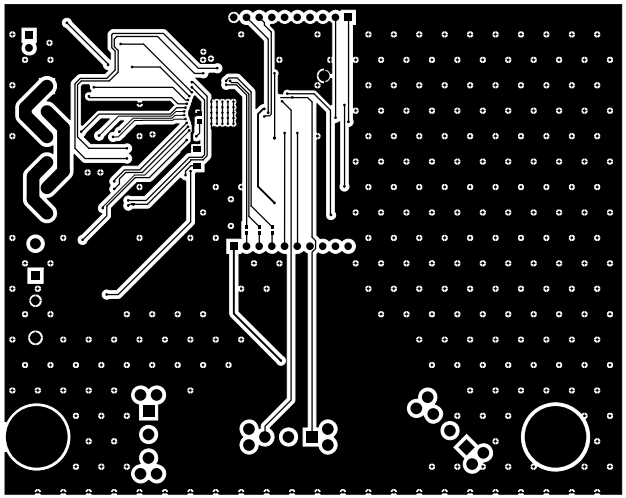
CAMtasticDXP (TM): tida-01330.gtl

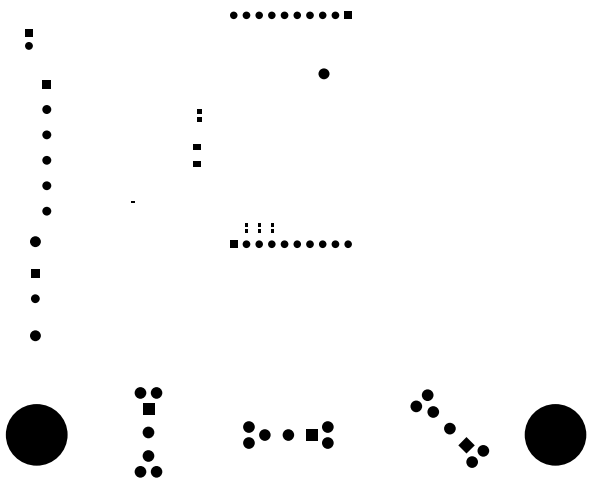


Top Layer

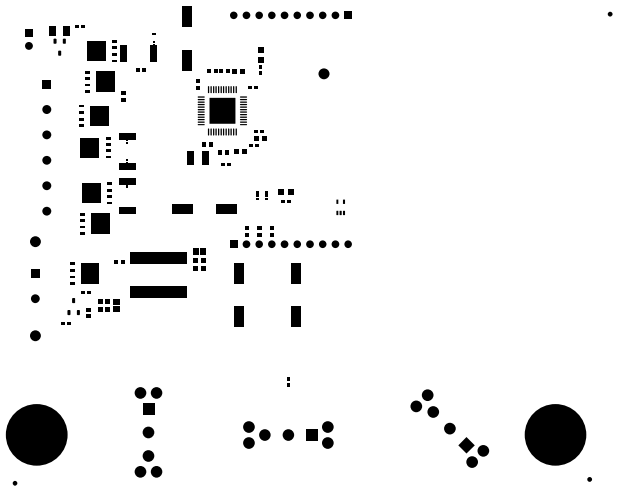


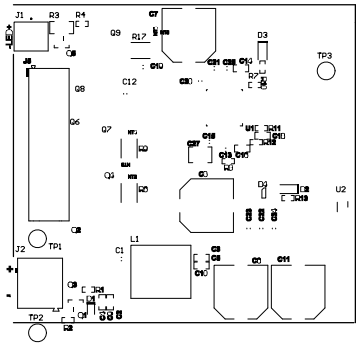
Bottom Layer

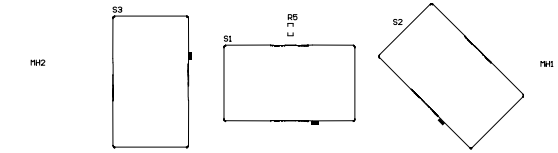
CAMtasticDXP (TM): tida-01330.gpb



CAMtasticDXP (TM): tida-01330.gpt



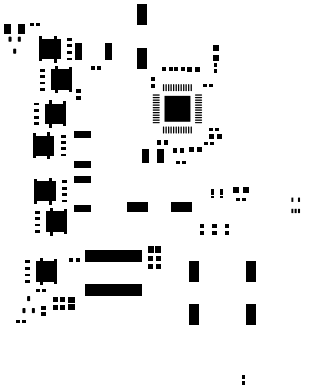




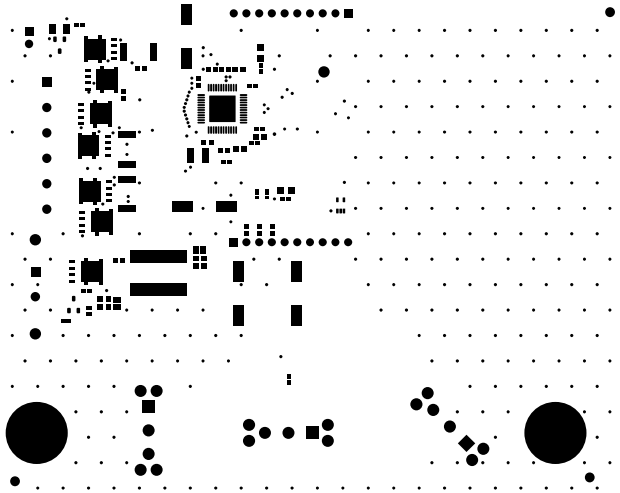
TIDA-01330

Pb-Free

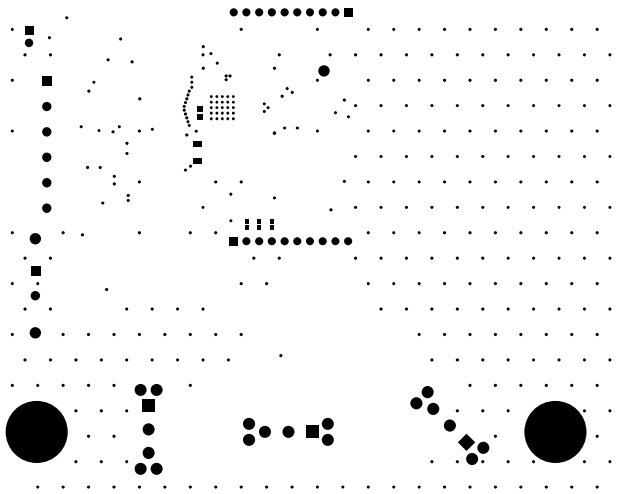
Top Overlay



Top Paste



Top Solder

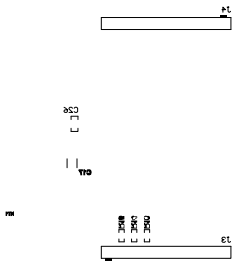


Bottom Solder

CAMtasticDXP (TM): tida-01330.gbp

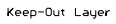
Bottom Paste

CAMtasticDXP (TM): tida-01330.gbo



Bottom Overlay

CAMtasticDXP (TM): tida-01330.gko



CAMtasticDXP (TM): tida-01330.gm1

M1 Board Outline

CAMtasticDXP (TM): tida-01330.gm2

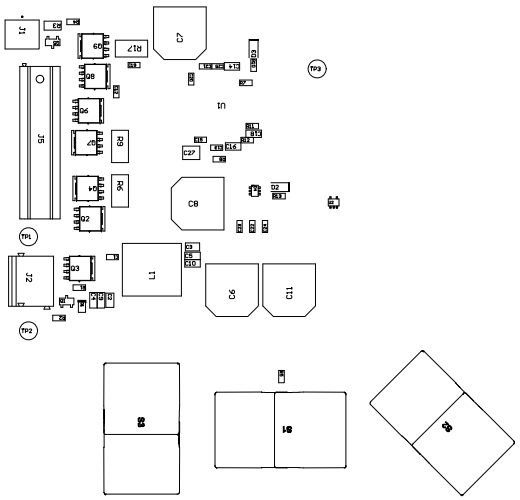
M2 Board Dimensions

CAMtasticDXP (TM): tida-01330.gm3

M3 3D STEP Top

CAMtasticDXP (TM): tida-01330.gm4

CAMtasticDXP (TM): tida-01330.gm5



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01330	REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-01330		
PLOT NAME = TIDA-01330.GM5	GENERATED : 1/6/2017 10:44:27 AM		TEXAS INSTRUMENTS

CAMtasticDXP (TM): tida-01330.gm6

J4

J3

J2

J1

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01330	REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-01330		
PLOT NAME = TIDA-01330.GM6	GENERATED : 1/6/2017 10:44:28 AM		TEXAS INSTRUMENTS

CAMtasticDXP (TM): tida-01330.gm9

M9 Title Sheet

TEXAS INSTRUMENTS

PROJECT TITLE: Automotive 2-Axis Power Seat Driver

DESIGNED FOR: Public Release

FILE NAME: TIDA-01330.PcbDoc

ENGINEER: Clark Kinnaird

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION: 16.1.12.290

DESIGN INFORMATION
MIN. TRACK WIDTH: 8 MIL MIN. CLEARANCE: 0.2 mm MIN. VIA PAD SIZE: 24 MIL MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL
MATERIAL: [ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____ THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____ TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/- _____ BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2 [ ] OTHER +/- _____ DRILLING: REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER _____ BOARD FINISH: SILKSCREEN: [X] TOP [X] BOTTOM SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____ SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____ [X] MATTE [ ] SEMI-GLOSS SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG [ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____ ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE [ ] N.C. ROUTE [X] V. SCORE CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF: [X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3 [X] RoHS [ ] OTHER PER ORDER ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER ADDITIONAL REQUIREMENTS: MICROSECTION: [ ] YES BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

M10 Fab Notes

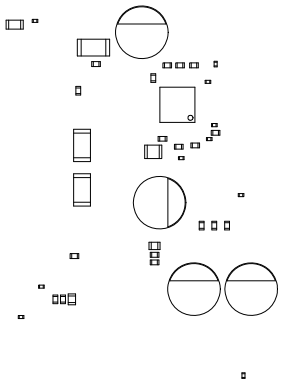
CAMtasticDXP (TM): tida-01330.gm11

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01330	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01330		
PLOT NAME = TIDA-01330.GM11	GENERATED : 1/6/2017 10:44:28 AM		TEXAS INSTRUMENTS

CAMtasticDXP (TM): tida-01330.gm12

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

M12 Stackup

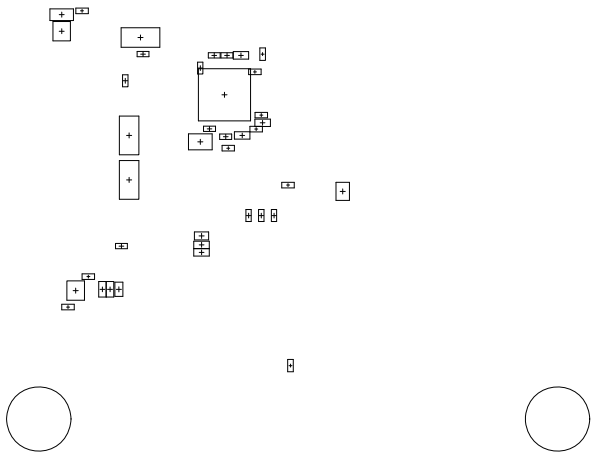


M13 Component Bodies Top

CAMtasticDXP (TM): tida-01330.gm14

M14 Component Bodies Bottom

CAMtasticDXP (TM): tida-01330.gm15



M15 Courtyards Top

CAMtasticDXP (TM): tida-01330.gm16

M16 Courtyards Bottom

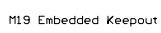
CAMtasticDXP (TM): tida-01330.gm17

M17 Embedded Cavity

CAMtasticDXP (TM): tida-01330.gm18

M18 Embedded Assembly

CAMtasticDXP (TM): tida-01330.gm19



IMPORTANT NOTICE FOR TI DESIGN INFORMATION AND RESOURCES

Texas Instruments Incorporated ('TI") technical, application or other design advice, services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using any particular TI Resource in any way, you (individually or, if you are acting on behalf of a company, your company) agree to use it solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources.

You understand and agree that you remain responsible for using your independent analysis, evaluation and judgment in designing your applications and that you have full and exclusive responsibility to assure the safety of your applications and compliance of your applications (and of all TI products used in or for your applications) with all applicable regulations, laws and other applicable requirements. You represent that, with respect to your applications, you have all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. You agree that prior to using or distributing any applications that include TI products, you will thoroughly test such applications and the functionality of such TI products as used in such applications. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

You are authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING TI RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY YOU AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

You agree to fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of your non-compliance with the terms and provisions of this Notice.

This Notice applies to TI Resources. Additional terms apply to the use and purchase of certain types of materials, TI products and services. These include; without limitation, TI's standard terms for semiconductor products http://www.ti.com/sc/docs/stdterms.htm), evaluation modules, and samples (http://www.ti.com/sc/docs/sampterms.htm).

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265